

OL-TFA9882UK

WLCSP9: wafer level chip-size package; 9 bumps

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	26-5-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.461	-	1.491	1.521	mm
E	package width	1.241	-	1.271	1.301	mm
A	seated height	[tbd]	-	[tbd]	0.6	mm
A ₂	package height	0.34	-	0.36	0.38	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	9	-	



2. Package outline

WLCSP9: wafer level chip-size package; 9 bumps; body 1.49 x 1.27 mm TFA9882UK

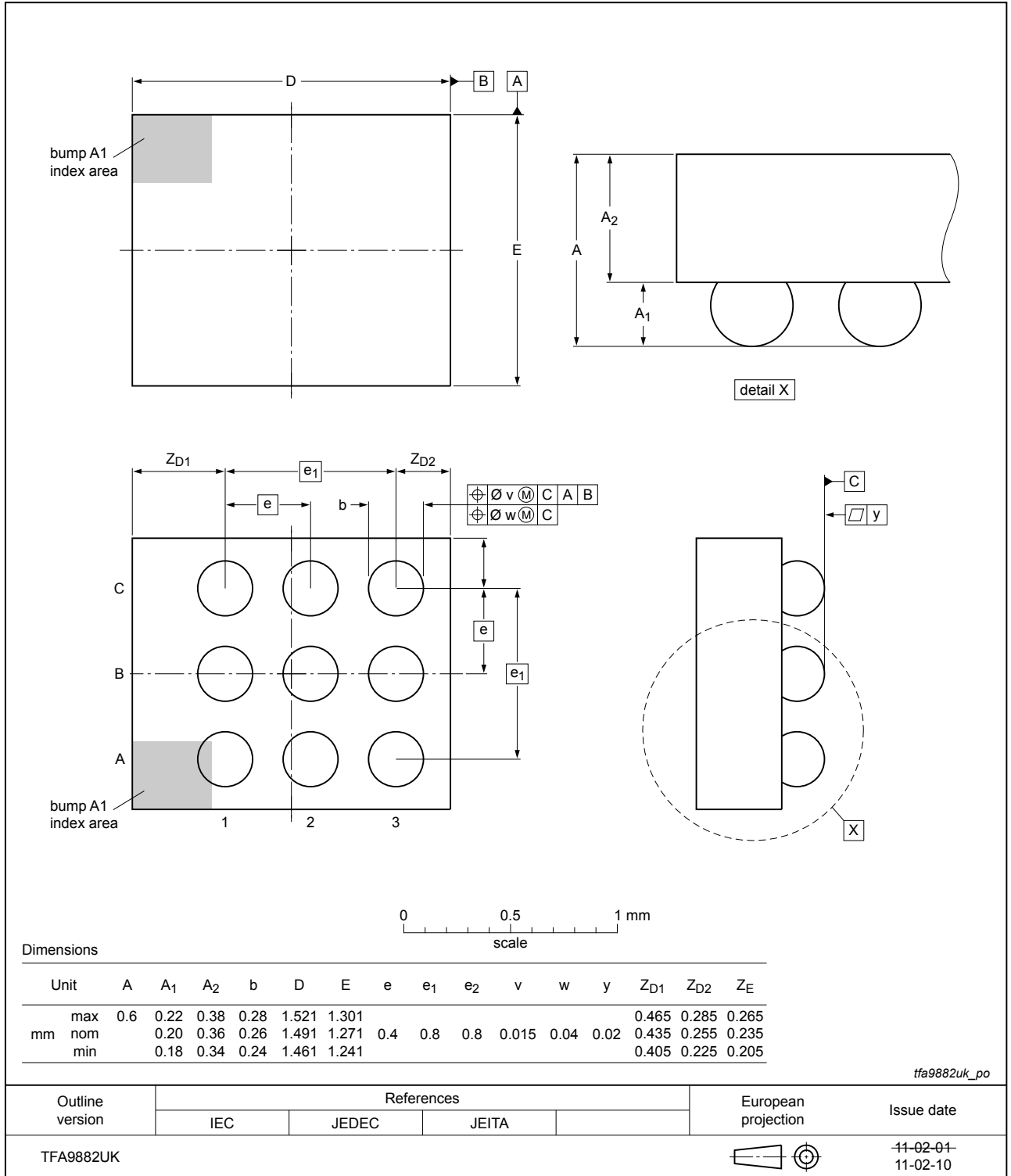


Fig. 1. Package outline WLCSP (OL-TFA9882UK)

3. Legal information

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